

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Terminals: Solder plated, solderable per MIL-STD-202F method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

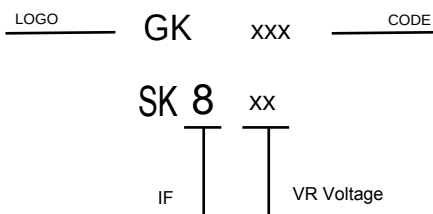
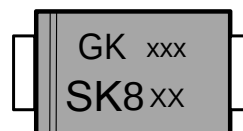


VOLTAGE RANGE

40 to 100 Volts

CURRENT

8.0 Ampere



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SK84	SK86	SK810	UNITS
Maximum Recurrent Peak Reverse Voltage	40	60	100	V
Maximum RMS Voltage	28	42	70	V
Maximum DC Blocking Voltage	40	60	100	V
Maximum Average Forward Rectified Current	8.0			A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150			A
Maximum Instantaneous Forward Voltage at 8.0A	0.55	0.7	0.85	V
Maximum DC Reverse Current Ta=25°C	150		50	uA
at Rated DC Blocking Voltage Ta=125°C	50		20	mA
Typical Junction Capacitance (Note1)	400			pF
Typical Thermal Resistance R _{JL} (Note 2)	16			°C/W
Operating Temperature Range T _J	-55 to +150			°C
Storage Temperature Range T _{STG}	-55 to +150			°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

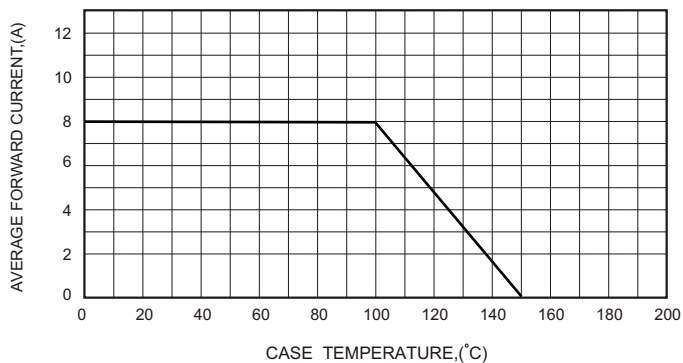


FIG.2-TYPICAL FORWARD CHARACTERISTICS

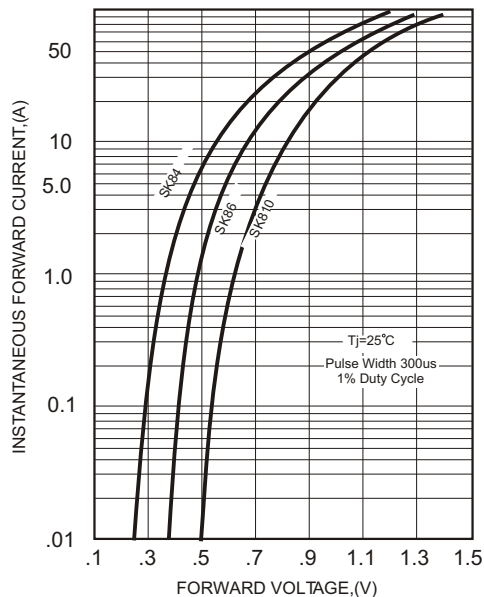


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

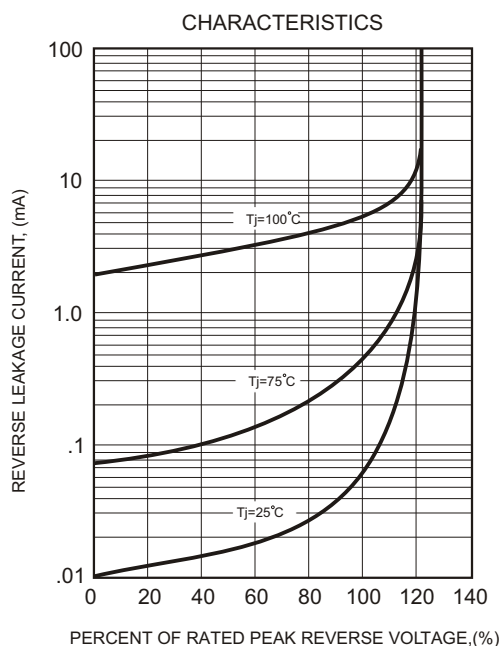


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

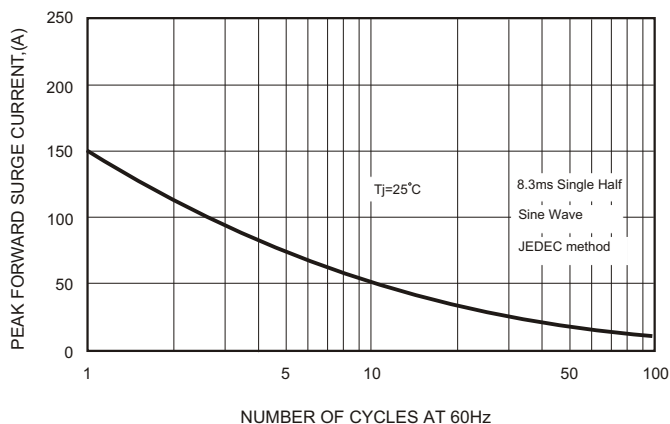
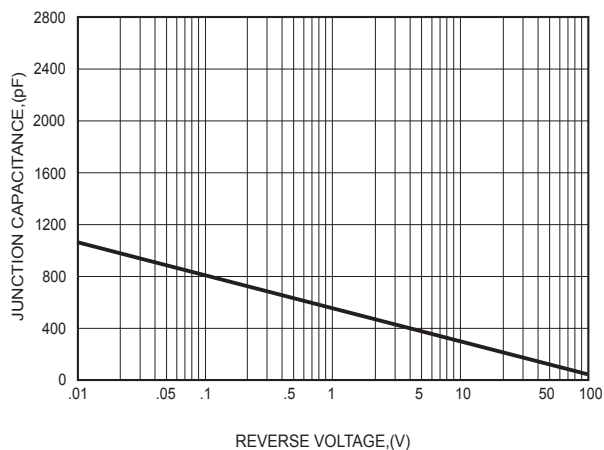
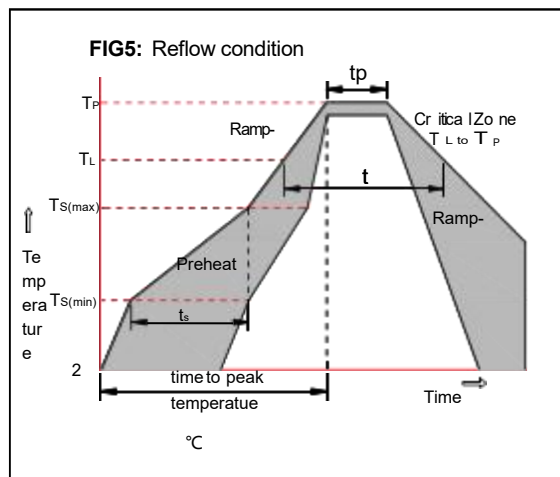


FIG.5-TYPICAL JUNCTION CAPACITANCE



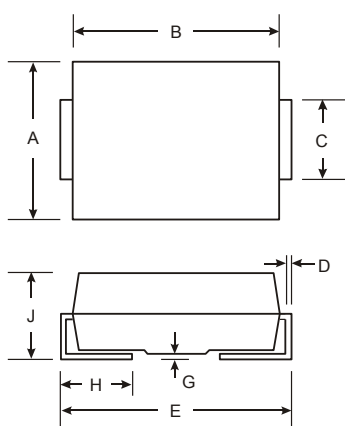
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

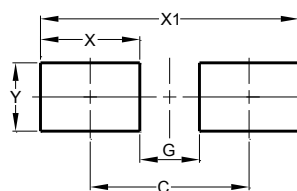


Package Dimensions & Suggested Pad Layout

SMB



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.11
D	0.15	0.31
E	5.08	5.59
G		0.20
H	0.76	1.50
J	2.13	2.44
All Dimensions in mm		



Dimensions	Value (in mm)
C	4.70
G	2.20
X	2.50
X1	7.20
Y	2.80

Tape		Symbol	Dimension (mm)
SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.20
		D1	1.60±0.20
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	4.00±0.20
		B0	5.45±0.20
K0	2.50±0.25		
T	0.20±0.10		
D2 D4 D3 W1		D2	330.0±5.0
		D3	73.0Min.
		D4	14.0±2.5
		W1	16.0±2.5
		Quantity: 3000PCS	